



仁懋电子

MOT1120T
N-MOSFET 100V,1.62mΩ ,280A

Features

- Uses MOT advanced double trench technology
- Low On-Resistance ($R_{DS(on)} \leq 2.0\text{m}\Omega$)
- Low Gate Charge
- Low Reverse transfer capacitances
- 100% avalanche tested
- Pb-free plating; RoHS compliant

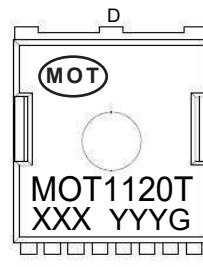
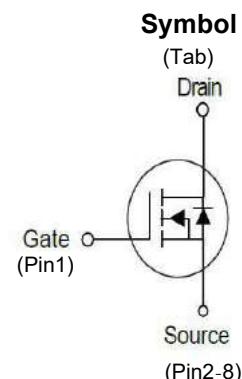
Applications

- Battery management
- Motor control and drive
- Synchronous rectification
- Switching applications

Pin configuration (Top view)



TOLL-8



G S S S S S S S S
XXX=Lot Number
YYY=Year Week
G=V_{th} Range

Marking

Parameter	Value	Unit
V_{DS}	100	V
$R_{DS(on)}$,typ.	1.62	$\text{m}\Omega$
I_D	280	A

Ordering information

Type/Ordering Code	Package	Marking	Packing&Qty.(pcs)
MOT1120T	TOLL-8	MOT1120T	2000/Reel

■ ABSOLUTE MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

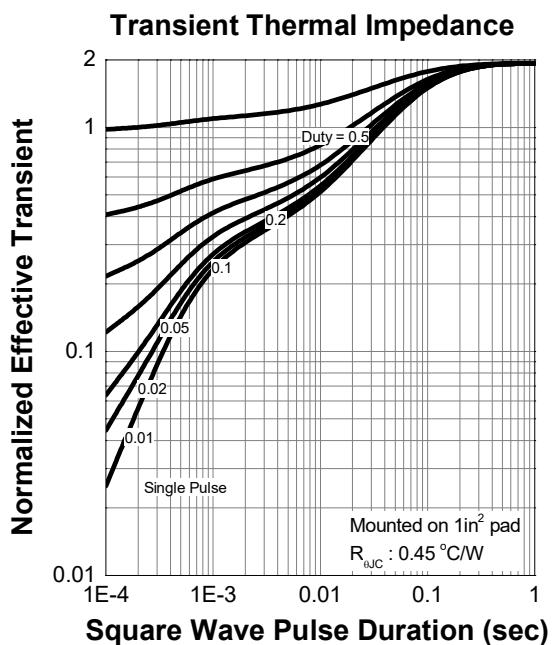
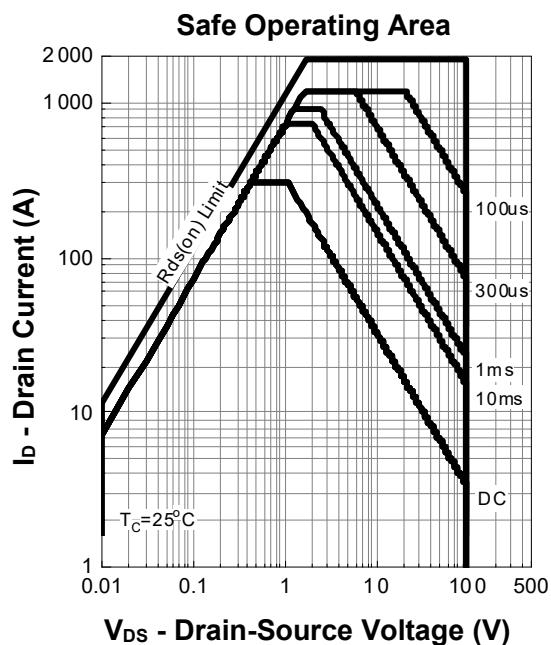
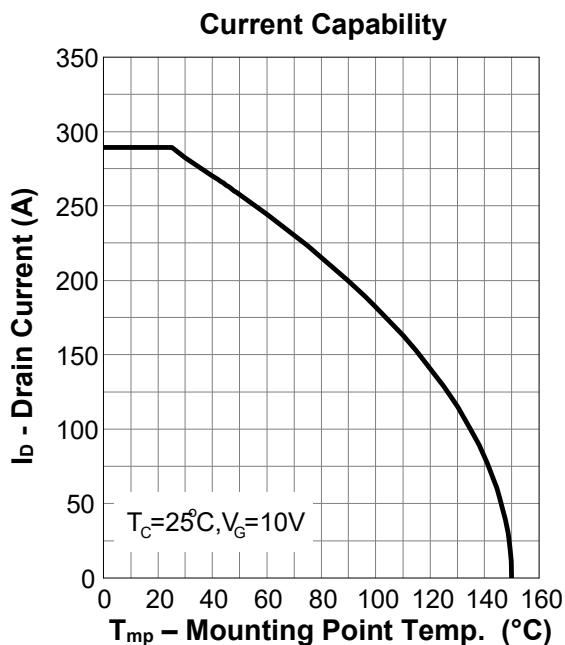
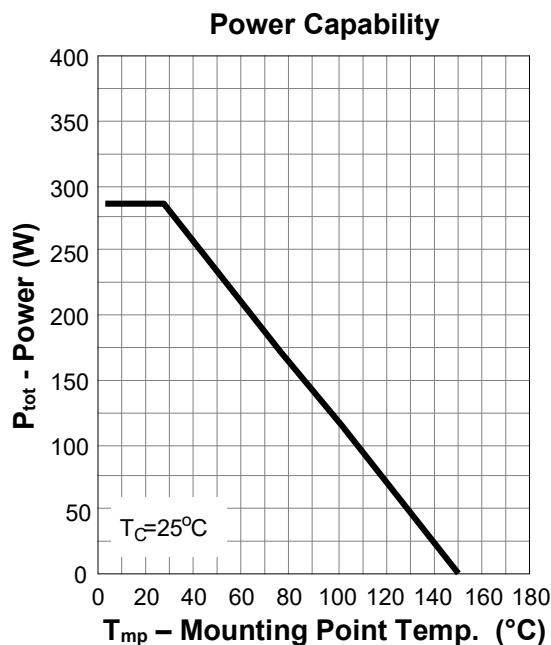
Parameter	Symbol	Conditions	Min	Typ	Unit
Drain-Source Voltage	V _{DS}	T _C = 25 °C	100	-	V
Gate-Source Voltage	V _{GS}	T _C = 25 °C	-	± 20	V
Drain Current (DC) *	I _D	T _C = 25 °C, V _{GS} = 10 V	-	280	A
		T _C = 100 °C, V _{GS} = 10 V	-	190	A
Drain Current (Pulsed)***	I _{DM}	T _C = 25 °C, V _{GS} = 10 V	-	1200	A
Drain power dissipation	P _{tot}	T _C = 25 °C	-	278	W
Storage Temperature	T _{stg}		- 55	150	°C
Junction Temperature	T _J		-	150	°C
Continuous-Source Current	I _S	T _C = 25 °C	-	280	A
Single Pulsed Avalanche Energy	E _{AS}	V _{DD} = 40 V, L= 1.0 mH	-	2162	mJ
Thermal Resistance- Junction to Ambient**	R _{θJA}		-	32.8	°C/W
Thermal Resistance- Junction to Case**	R _{θJC}		-	0.45	°C/W

■ ELECTRICAL CHARACTERISTICS ($T_C=25^\circ\text{C}$, unless otherwise specified)

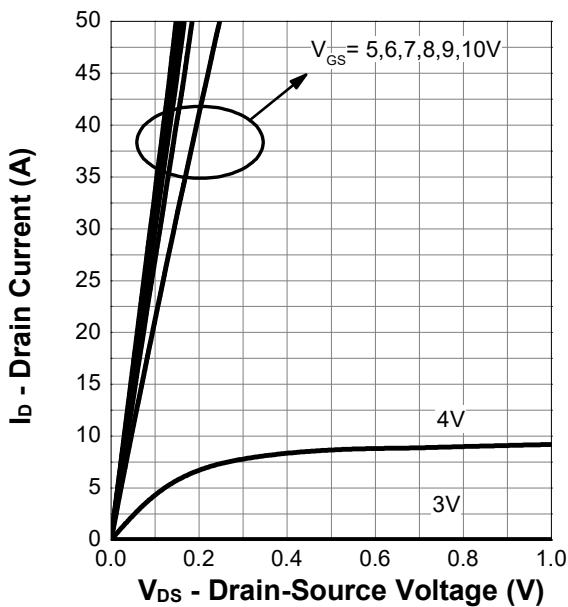
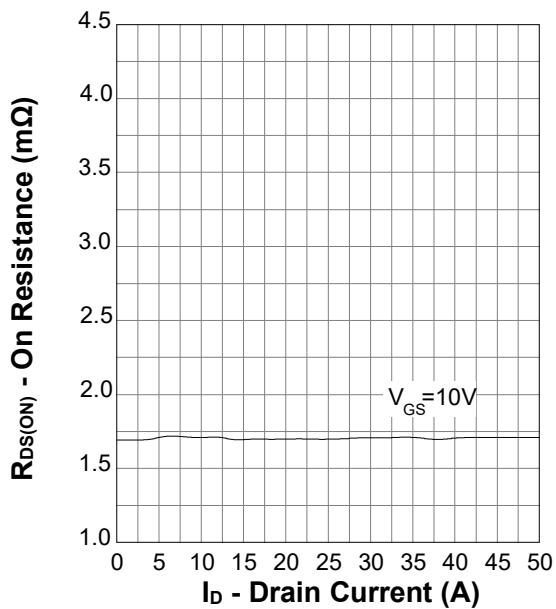
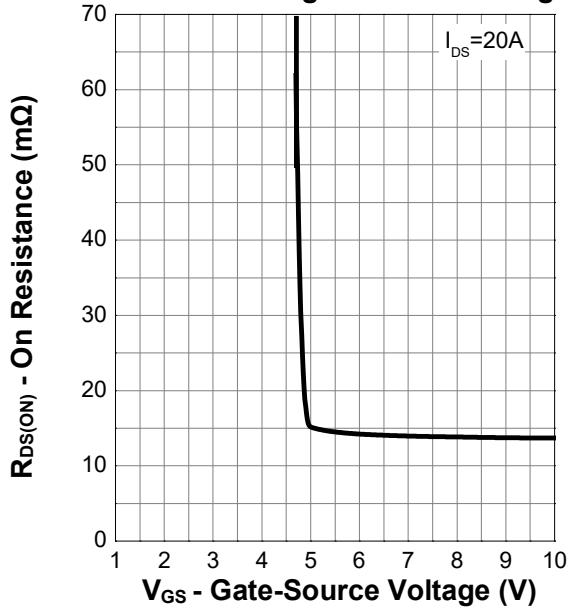
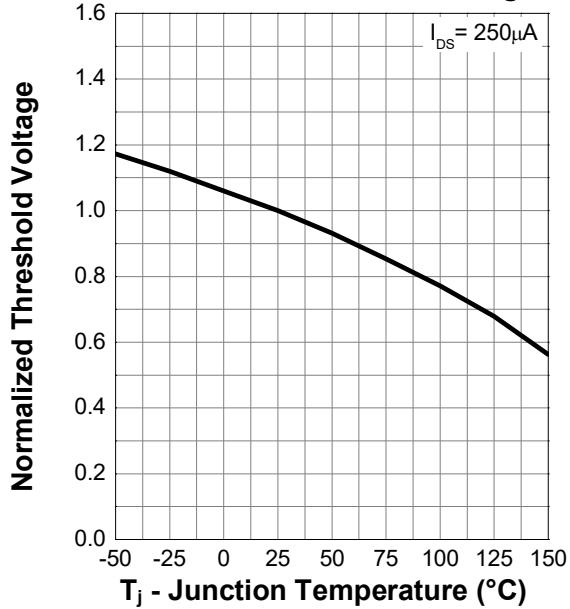
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0 \text{ V}, I_{\text{DS}} = 250 \mu\text{A}$	100	-	-	V
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}} = V_{\text{GS}}, I_{\text{DS}} = 250 \mu\text{A}$	2	-	4	V
Drain Leakage Current	I_{DSS}	$V_{\text{DS}} = 80 \text{ V}, V_{\text{GS}} = 0 \text{ V}$	-	-	1	μA
Gate Leakage Current	I_{GSS}	$V_{\text{GS}} = \pm 20 \text{ V}, V_{\text{DS}} = 0 \text{ V}$	-	-	± 100	nA
On-State Resistance ^a	$R_{\text{DS(ON)}}$	$V_{\text{GS}} = 10 \text{ V}, I_{\text{DS}} = 20 \text{ A}$	-	1.62	2.0	$\text{m}\Omega$
Diode Characteristics						
Diode Forward Voltage ^a	V_{SD}	$I_{\text{SD}} = 20 \text{ A}, V_{\text{GS}} = 0 \text{ V}$	-	-	1.3	V
Reverse Recovery Time	t_{rr}	$I_{\text{DS}} = 20 \text{ A}, V_{\text{GS}} = 0 \text{ V}$	-	80	-	nS
Reverse Recovery Charge	Q_{rr}	$dI^{\text{SD}}/dt = 100 \text{ A}/\mu\text{s}$	-	195	-	nC
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0 \text{ V}, V_{\text{DS}} = 20 \text{ V}$ Frequency = 1 MHz	-	11000	-	pF
Output Capacitance	C_{oss}		-	4000	-	pF
Reverse Transfer Capacitance ^b	C_{rss}		-	1200	-	pF
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DS}} = 50 \text{ V}, V_{\text{GEN}} = 10 \text{ V},$ $R_G = 4.5 \Omega, R_L = 2.5 \Omega,$ $I_{\text{DS}} = 20 \text{ A}$	-	32	-	nS
Turn-on Rise Time	t_r		-	40	-	nS
Turn-off Delay Time	$t_{\text{d(off)}}$		-	80	-	nS
Turn-off Fall Time	t_f		-	35	-	nS
Gate Charge Characteristics ^b						
Total Gate Charge	Q_g	$V_{\text{DS}} = 50 \text{ V}, V_{\text{GS}} = 10 \text{ V},$ $I_{\text{DS}} = 20 \text{ A}$	-	131	-	nC
Gate-Source Charge	Q_{gs}		-	50	-	nC
Gate-Drain Charge	Q_{gd}		-	24.5	-	nC

Notes :

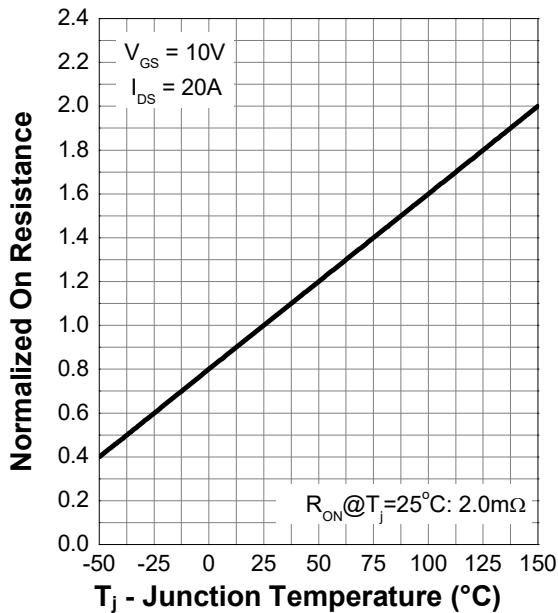
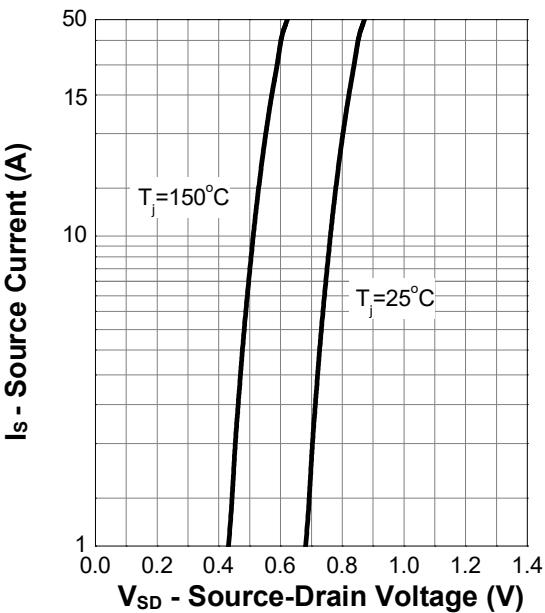
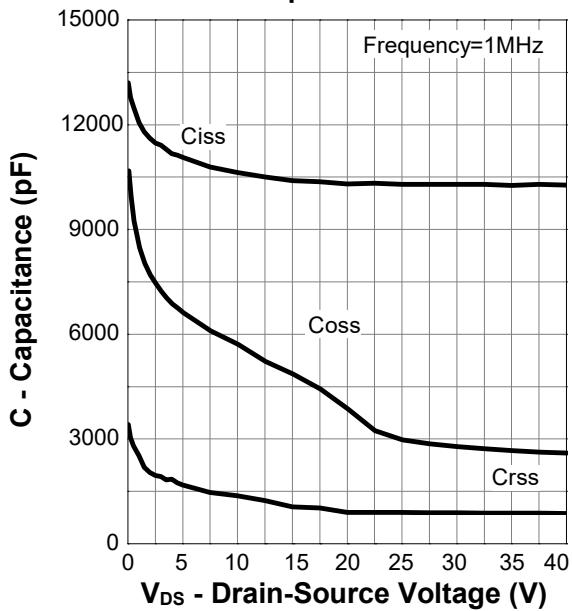
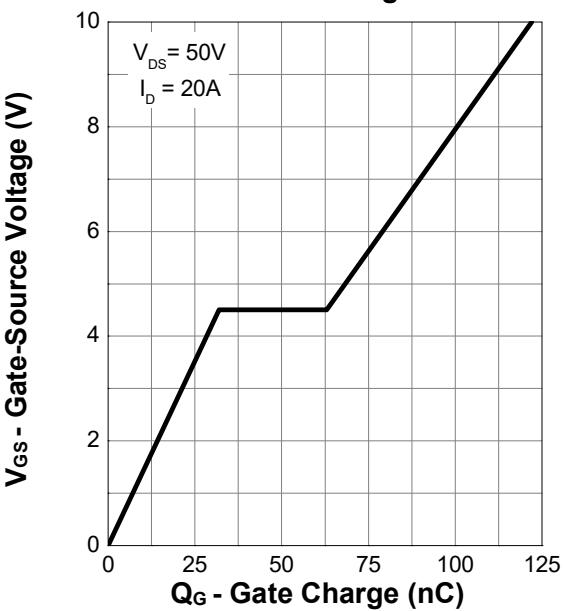
- * Pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2 \%$
- ** Surface Mounted on minimum footprint pad area.
- *** Limited by bonding wire
- a : Pulse test ; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$
- b : Guaranteed by design, not subject to production testing

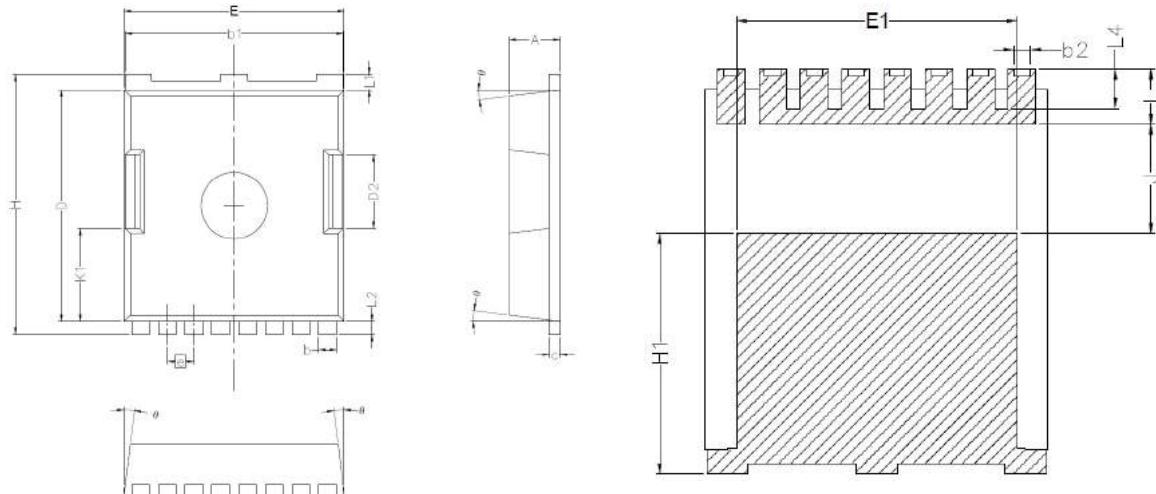
■ TYPICAL CHARACTERISTICS


■ TYPICAL CHARACTERISTICS(Cont.)

Output Characteristics**On Resistance****On-resistance gate source voltage****Normalized Threshold Voltage**

■ TYPICAL CHARACTERISTICS(Cont.)

Normalized On Resistance

Diode Forward Current

Capacitance

Gate Charge


■TOLL-8L PACKAGE OUTLINE DIMENSIONS


Symbol	Dimensions In Millimeters	
	Min.	Max.
A	2.20	2.40
b	0.70	0.90
b1	9.70	9.90
b2	0.42	0.50
c	0.40	0.60
D	10.28	10.58
D2	3.10	3.50
E	9.70	10.10
E1	7.90	8.30
e	1.20BSC	
H	11.48	11.88
H1	6.75	7.15
N	8	
J	3.00	3.30
K1	3.98	4.38
L	1.40	1.80
L1	0.60	0.80
L2	0.50	0.70
L4	1.00	1.30
θ	4°	10°

- The information contained hSurface-mounted package Advnced terch cell design Super trencherein is subject to change without notice.
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